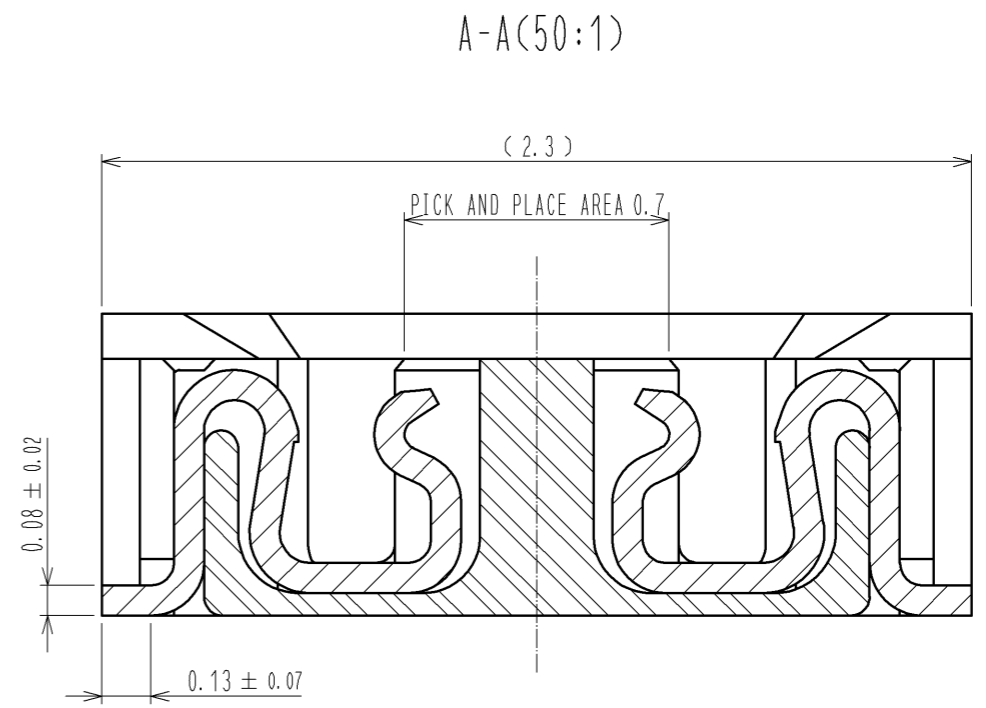
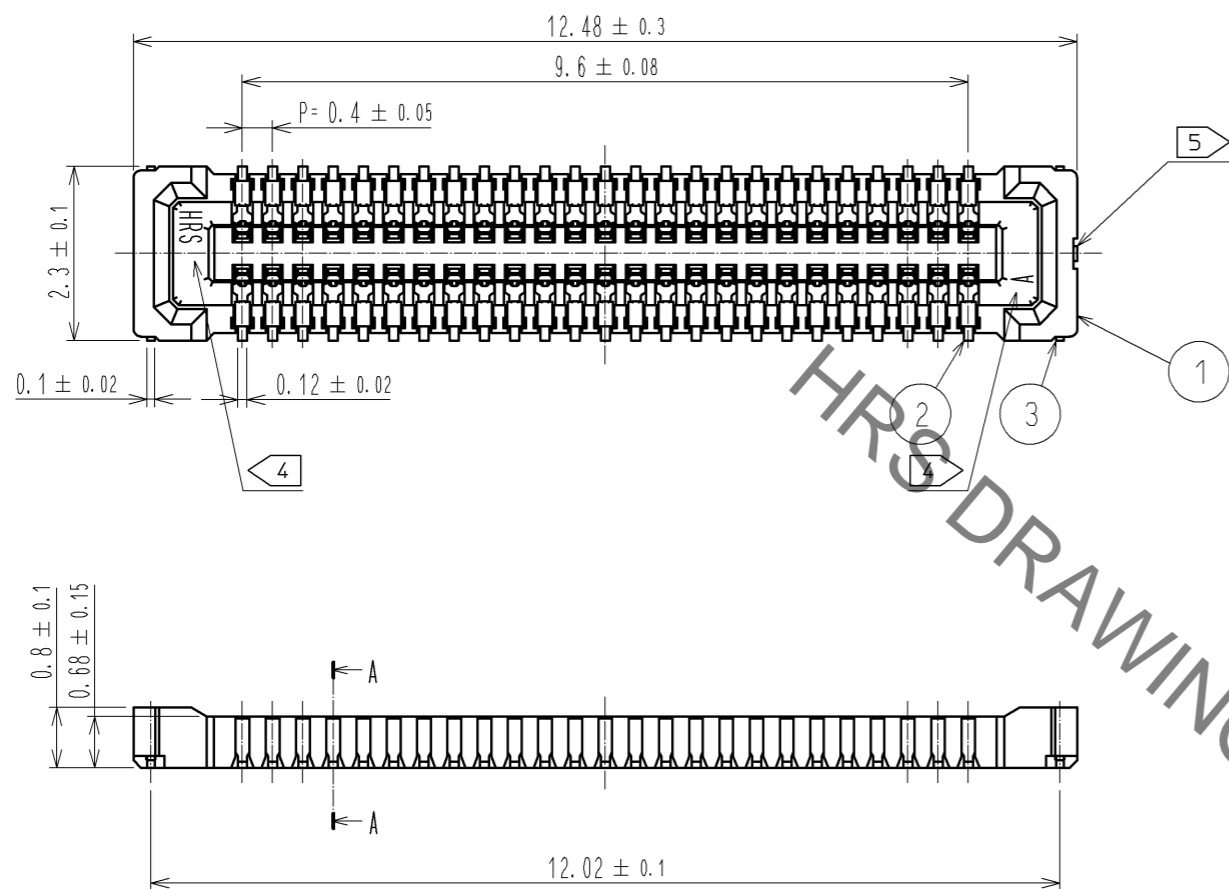




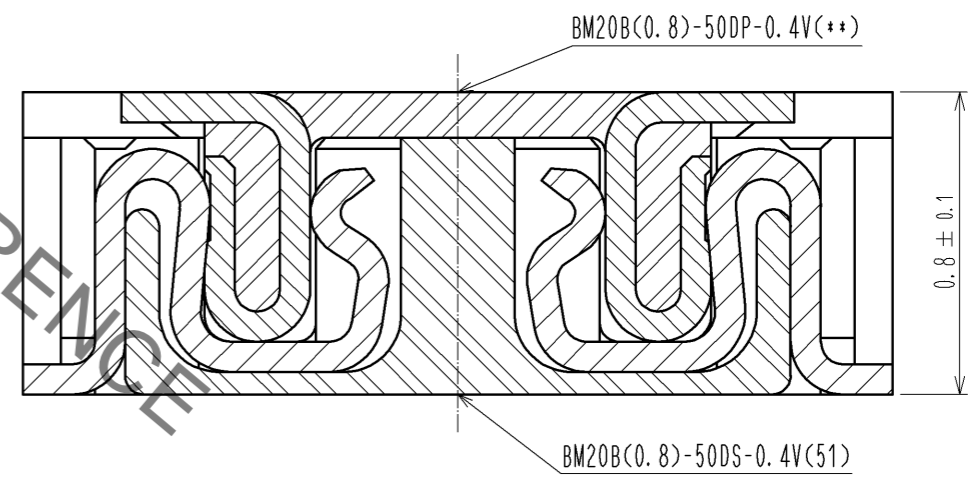
**THE DATASHEET OF
BM20B(0.8)-50DS-0.4V(51)**



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ENGAGEMENT FIGURE (50:1)



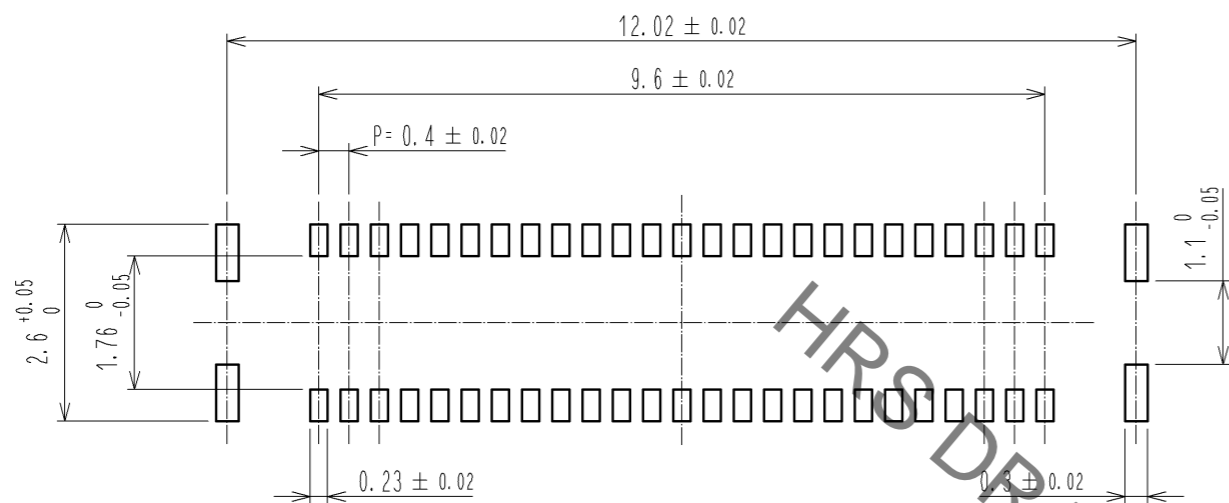
- NOTE 1 . ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
- 2 CONTACT PLATING SPECIFICATIONS
CONTACT AREA : GOLD 0.05 μm MIN
SMT LEAD : GOLD 0.05 μm MIN
UNDERPLATING : NICKEL 1 μm MIN
(SURFACE : SEALING)
 - 3 METAL FITTING PLATING SPECIFICATIONS
SMT LEAD : GOLD 0.05 μm MIN
UNDERPLATING : NICKEL 1 μm MIN
(SURFACE : SEALING)
 - 4 HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.
 - 5 GATE POSITION IS INDICATED IN APPROX POSITION SHOWN.

NO.	MATERIAL	FINISH .	REMARKS	NO.	MATERIAL	FINISH .	REMARKS
4	PS		CLEAR (EMBOSSED CARRIER TAPE)				
3	BRASS	3		7	PS		CLEAR (REINFORCEMENT COLLAR)
2	PHOSPHOR BRONZE	2		6	PS		BLACK (PLASTIC REEL)
1	LCP		UL94 V-0, BLACK	5	POLYESTER		CLEAR (COVER TAPE)

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	10:1	△				
APPROVED : KH. IKEDA			12.03.15	DRAWING NO. EDC3-332319-01		
CHECKED : TS. MIYAZAKI			12.03.15	PART NO. BM20B(0.8)-50DS-0.4V(51)		
DESIGNED : YK. SATAKE			12.03.14	CODE NO. CL684-9013-4-51		
DRAWN : KR. AJITO			12.03.14	1/3		

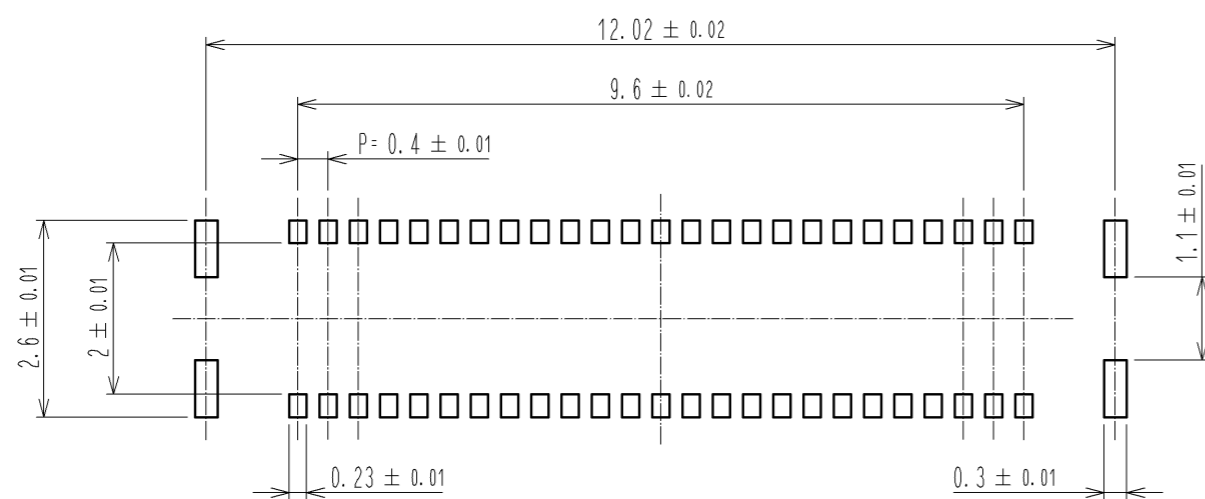
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◆ RECOMMENDED PCB LAYOUT

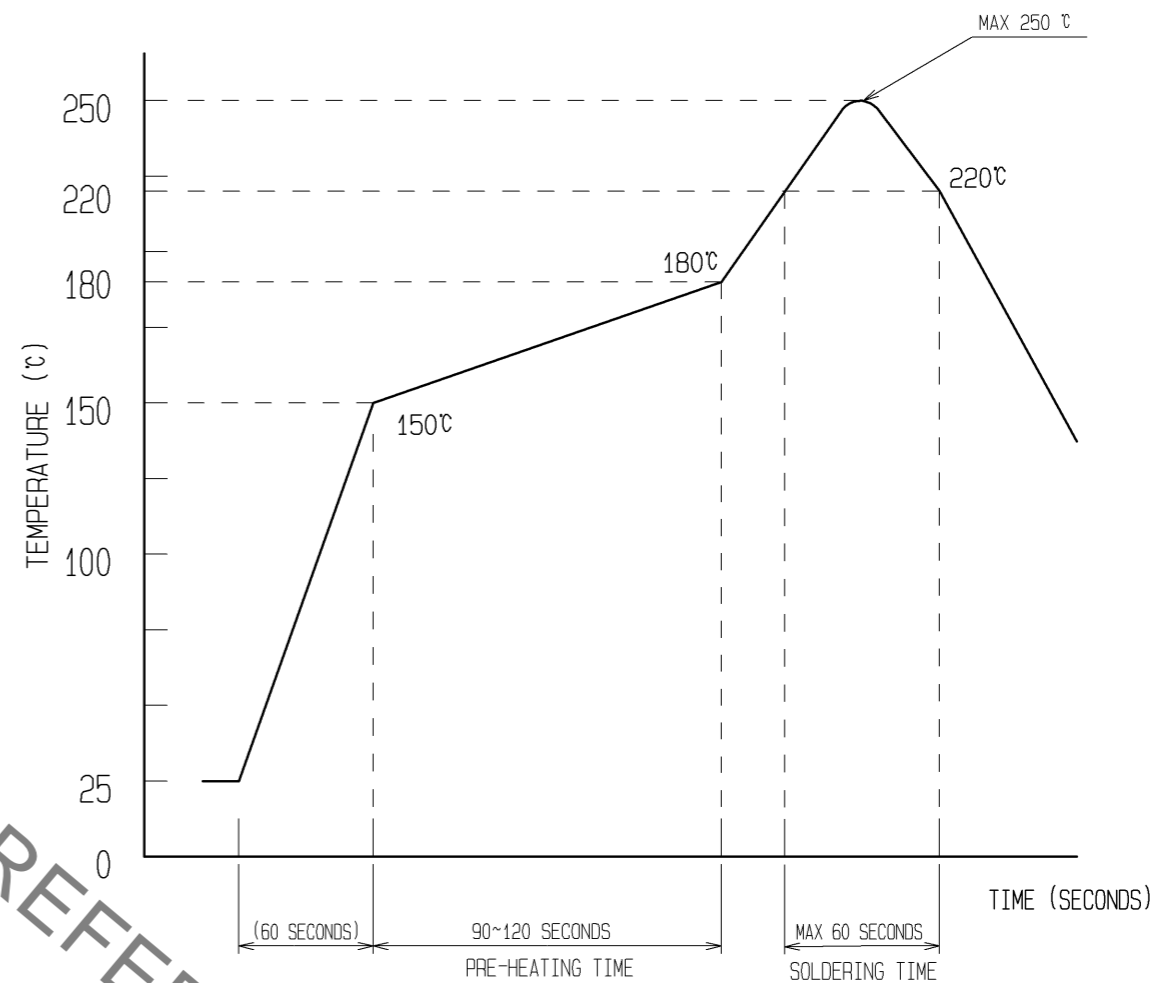


◆ RECOMMENDED METAL MASK DIMENSIONS

MATAL MASK THICKNESS : 100 μm



⑥ RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



- REFLOW METHOD : IR REFLOW
 NUMBER OF REFLOW CYCLES : 2 CYCLES MAX.
 1) REFLOW TIME
 DURATION ABOVE 220°C. 60 SEC MAX.
 (PEAK TEMPERATURE : 250°C MAX)
 2) PRE-HEAT TIME
 PRE-HEAT TEMPERATURE(MIN): 150°C
 PRE-HEAT TEMPERATURE(MAX): 180°C
 PRE-HEAT TIME: 90-120 SEC.

⑥ THE TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.
 ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND
 OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE,
 A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED
 PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS	DRAWING NO.	EDC3-332319-01
	PART NO.	BM20B(0.8)-50DS-0.4V(51)
	CODE NO.	CL684-9013-4-51

△ 2/3

Looking for pricing, stock, or lifecycle information?

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- ⊖ [View BM20B\(0.8\)-50DS-0.4V\(51\) on WIN SOURCE](#)
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- ✓ Alternative Solution
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